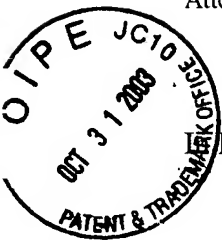


2826



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of:

Scot A. Kellar et al.

Examiner: Williams, Alexander O.

U.S. Serial No: 10/066,643

Art Unit: 2826

Filed: February 6, 2002

For: WAFER BONDING FOR 3-D
INTEGRATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RECEIVED
NOV-5 2003
TECHNOLOGY CENTER 2800

RESPONSE TO ELECTION REQUIREMENT

Sir:

In response to the Election Requirement mailed October 1, 2003, applicant(s) hereby elects to prosecute Group I claims, claims 1-7 and 15-20 drawn to a three-dimensional (3-D) integrated chip system. As such, applicant(s) elects to withdraw Group II claims 8-14 drawn to making a wafer bonding method.

If there are any additional charges, please charge Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN

Date: 10/27/03

Michael A. Bernadicou
Reg. No. 35,934

12400 Wilshire Blvd.,
Seventh Floor
Los Angeles, CA 90025-1026
(408) 720-8300